Insight™ software for Reflow Tracker® now supports the specialized analysis needed to monitor wave soldering. The Wave Solder Analysis Kit allows you to adapt your Reflow Tracker temperature profiling system for monitoring the wave soldering process. Insight software can then be used to analyze data from both processes, ensuring compatibility of data throughout the factory and minimizing operator training needs.

You can view all the critical wave process parameters in one easy-to-read table. The wave, chip wave (if present) and pre-heat data will all be shown, together with the temperature profile graph.

The system uses a pallet to carry the data logger and thermal barrier through the process. The pallet incorporates fixed thermocouples ensuring accuracy and repeatability without the expense of a dedicated wave analyzer.

**SYSTEM FEATURES**
The Datapaq Wave Solder Analysis Kit enables you to profile actual PCB/component temperatures, or alternatively, using the pallet with its integral PCB Coupon the process stability can be monitored. The results are clearly shown for the pre-heat and wave areas of the process.

*Pre-heat analysis includes:*
- Maximum slopes
- Rise times
- Maximum temperature in the pre-heat zone
- Delta at the wave
- Maximum temperature over the wave

*Wave analysis includes:*
- Contact time (left and right)
- Contact length (left and right)
- Parallelism
- Line speed

**WIZARDS**
Wizards are designed to guide you step-by-step through a particular process, while at each step giving you the opportunity to ‘back up’ to a previous step if you realize you have made a mistake.

**ALARMS IF THE PROFILE IS OUT OF TOLERANCE**
The software can be configured so that if the results are out of limits in the wave or pre-heat areas, an alarm condition is shown.
### PART NUMBERS

<table>
<thead>
<tr>
<th>Part Number</th>
<th>Description</th>
<th>Details</th>
</tr>
</thead>
<tbody>
<tr>
<td>CS3070</td>
<td>Wave Solder Pallet fitted with 3 thermocouples and a PCB Coupon</td>
<td>Enables reliable and repeatable monitoring of the pre-heat and wave soldering processes. Consists of the pallet fitted with PA1321, PA1320 thermocouples and CS3072 PCB Coupon. Dimensions (H x W x L) 40 mm x 300 mm x 350 mm (1.5 in x 11.8 in x 13.7 in) Can also be fitted with CS3071 Wave Glass Check Panel.</td>
</tr>
<tr>
<td>CS3071</td>
<td>Wave Glass Check Panel</td>
<td>To be used with CS3070. Enables quick visual check of wave contact, length and uniformity. Dimensions 198 mm x 130 mm (7.7 in x 5.1 in)</td>
</tr>
<tr>
<td>CS3072</td>
<td>PCB Coupon</td>
<td>Fitted with 3x Type K thermocouples. To be used with CS3070. Enables the Datapaq system to measure the top and bottom pre-heat temperatures in the wave process.</td>
</tr>
<tr>
<td>CS1320/I</td>
<td>Wave Thermocouples</td>
<td>Thermocouples for use on CS3070 Wave Solder Pallet</td>
</tr>
<tr>
<td>SW5060</td>
<td>Reflow Tracker Insight Software</td>
<td>The wave solder analysis kit is designed for use with Reflow Tracker Insight software. It is compatible with the full range of Q18 data loggers, with the exception of the DQ1861. Datapaq provides a wide range of data loggers and thermal barriers to suit nearly any reflow or wave solder application. Please contact us for more information.</td>
</tr>
</tbody>
</table>

The Datapaq approach is to offer you maximum flexibility when selecting how to monitor the wave process. Choose from the following:

- Datapaq Wave Solder Pallet with integral PCB Coupon – for regular repeatable process monitoring
- Datapaq Wave Solder Pallet with remaining thermocouples attached to customer product – for monitoring wave stability and actual PCB/component temperatures in the process

Use Insight™ analysis software to monitor both reflow soldering and wave soldering processes. This reduces the needs for operator training on multiple systems and ensures consistency of data throughout the manufacturing area. The software is fully network compatible, enabling profile data to be shared within the same site.

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**The Worldwide Leader in Temperature Profiling**